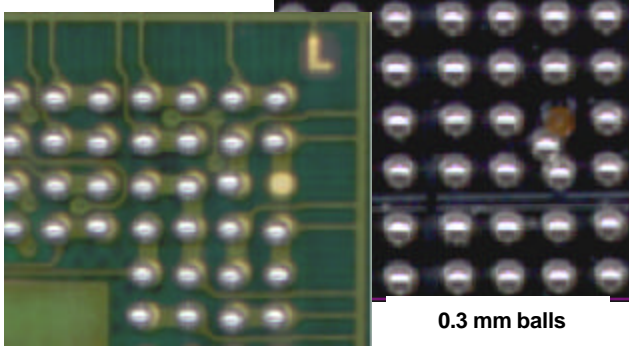


ScanEYE BALL™

"Ball Placement Inspection"



0.3 mm balls

WHAT IS ScanEYE BALL?

ScanEYE BALL provides a simple and user-friendly alternative to inaccurate and time-consuming manual inspection methods or expensive high-end AOI systems.

ScanEYE BALL uses a simple Windows user interface integrated with an image-processing unit. This combination allows 100% inspection of ball or bump placement on a wide variety of substrates and device types including FR4, Ceramic, Wafer, Flip chip, BGA, CSP, etc. The system can be used either pre or post reflow.

HOW DOES ScanEYE BALL WORK?

ScanEYE BALL's integration within the production environment provides inspection of ball or bump:

- Presence/Absence
- Size
- Position

Each device or substrate is placed into ScanEYE BALL for 100% inspection. The balls or bumps are inspected and any errors are displayed on the screen. No more surprises!

FAST & SIMPLE PROGRAMMING

ScanEYE BALL is quickly programmed from a golden part in a few minutes. Corrections to the golden part can be quickly and easily made, if necessary.

INCREASE YIELD & IMPROVE OVERALL EQUIPMENT EFFICIENCY

ScanEYE BALL's powerful 100% inspection process increases product yield by ensuring accurate ball or bump placement. Missing balls or bumps can result in reduced yield, lost production time and extensive rework.

Missing or misplaced balls or bumps are now automatically detected. Problems are identified and eliminated before substrates or devices are reflowed, permitting quick and easy rework.

SIMPLICITY

ScanEYE BALL set up is fast and easy. In production, each device or substrate placed on the table is shuttled in, automatically aligned and checked for accuracy with a PASS or FAIL inspection in seconds.

WHY USE ScanEYE BALL?

- Mandatory: 100% automatic inspection of ball or bump placement, pre and/or post reflow.
- Security: Confirm ball/bump absence / presence.
- Necessity: Detect errors before reflow permitting easy rework.
- Flexibility: System is tailored to meet specific customer's requirements.



DESKTOP MODULE

System Specifications*

- Maximum Substrate Size: 18" X 24" (457mm X 610mm)
 - Maximum Inspection Area: 11.7" X 16.5" (297mm X 419mm)
 - Ball/Bump Diameter Range: 0.050 mm to 6 mm
 - Resolution: 400/1000/2000/3200*/4000* dpi
- *Reduced Inspection area for 3200 & 4000 dpi.

Footprint of Inspection Unit

- Depth: 31.5" (800mm), table extended 49.5" (1,257mm)
- Width: 27.25" (692mm)
- Height: 19" (482mm)
- Weight: 150lbs. (55.95kg)

COMPUTER*

- Pentium IV (minimum 1GHz) Personal Computer
- 60 GB HD, 1GB RAM
- CD-ROM (CD-RW for archive purposes)
- Monitor (17" or larger)
- Printer
- Windows 2000
- 2 available USB ports

*Recommended customer supplied minimum PC requirements.



Partners: Avytechno Indonesia,
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